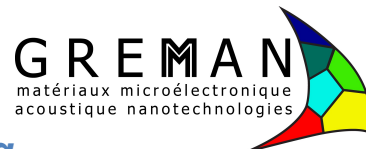




**CALL FOR PAPERS**  
**From Nano to Macro**  
**Power Electronics and Packaging**  
**European Workshop**  
**November the 24<sup>th</sup>, 2022 - TOURS, FRANCE**



Following the success of the *Power Electronics Workshop* organized over the past 12 years in partnership with GREMAN (UMR 7347) and Polytech-Tours, sponsored by ST-Microelectronics, CERTeM and Polytech Tours, IMAPS-France proudly announces the 13<sup>th</sup> edition of the *Power Electronics and Packaging Technical Workshop* to be held in Tours, France on **Thursday, November the 24<sup>th</sup>, 2022**. The city of Tours is located along the scenic Loire Valley which is famous for its castles built along the river. The event will be held in English for the 9<sup>th</sup> consecutive year. **Please, don't miss the date!!**

**TECHNICAL COMMITTEE:**

Laurent BARREAU	ST Microelectronics Tours	France	Chairman
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We invite speakers to submit abstracts relating to the following topics:

- Power management for transportation and industrial systems
- Energy harvesting systems, from nano to macro (smart grid, wind energy, photovoltaic, etc...)
- Energy conversion systems– from power to emission (lighting, ultrasonic, infrared, etc...)

These topics could be developed around several themes, such as:

- New materials and substrates dedicated to power electronics
- Thermal or thermo mechanical or regulatory constraints (RoHS regulation, REACH, etc...)
- Dedicated technologies for integration and optimisation of power systems, including passive components (weight and size reduction, yield improvement, efficiency, etc...)
- Innovative technologies, materials and processes dedicated to interconnection and packaging (die attach, bonding wire & ribbon wires, 3D power components, etc...)
- Reliability and failure modes (impacts linked to technologies, thermal constraints, radiation, etc...), predictive methods, design of experiments, reliability
- High current and high voltage or extremely high voltage: impact on packaging technologies

Presentations will be 25 minutes in length, including 5 minutes for questions and answers. The abstract submission deadline is July the 25<sup>th</sup>. Please submit abstracts in English (Conference official language) and word format, including the names of the company or institution, the speaker and associated author(s), the title of the conference and an abstract of 250-600 words. Paper acceptance will be communicated prior to September the 15<sup>th</sup>.

Following the first workshop day, IMAPS will organize in the evening a specific event followed by a diner.

For further information, please contact by E-mail: [imaps.france@orange.fr](mailto:imaps.france@orange.fr)

Website: <http://france.imapseurope.org/>

